

RKR0202AQE

Silicon Schottky Barrier Diode for Rectifying

REJ03G1699-0100
Rev.1.00
Jun 13, 2008

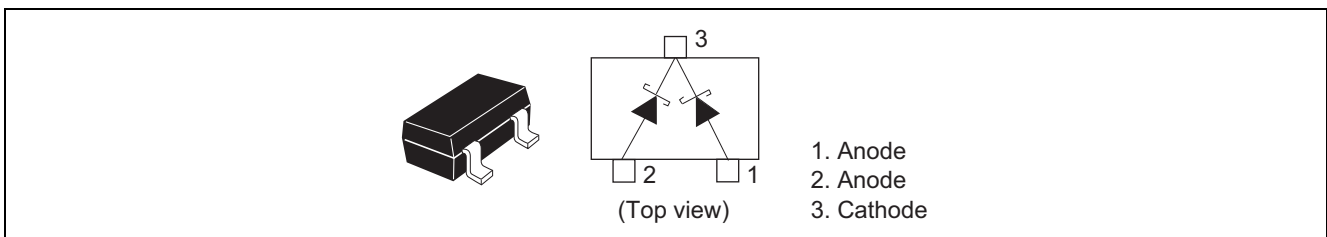
Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- CMPAK Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Part No.	Laser Mark	Package Name	Package Code
RKR0202AQE	E9	CMPAK	PTSP0003ZB-A

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RMM}	20	V
Average rectified current	I_O *1 *2	200	mA
Non-Repetitive peak forward surge current	I_{FSM} *3	2	A
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

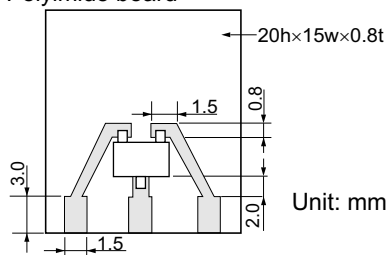
- Notes: 1. Two device total
 2. See from Fig.4 to Fig.6
 3. 10ms sine wave 1 pulse

Electrical Characteristics *1

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	—	—	0.30	V	$I_F = 10$ mA
	V_{F2}	—	—	0.40	V	$I_F = 100$ mA
Reverse current	I_R	—	—	50	μA	$V_R = 20$ V
Thermal resistance	$R_{th(j-a)}$	—	550	—	°C/W	Polyimide board *2

- Notes: 1. Per one device
 2. Polyimide board



Main Characteristic

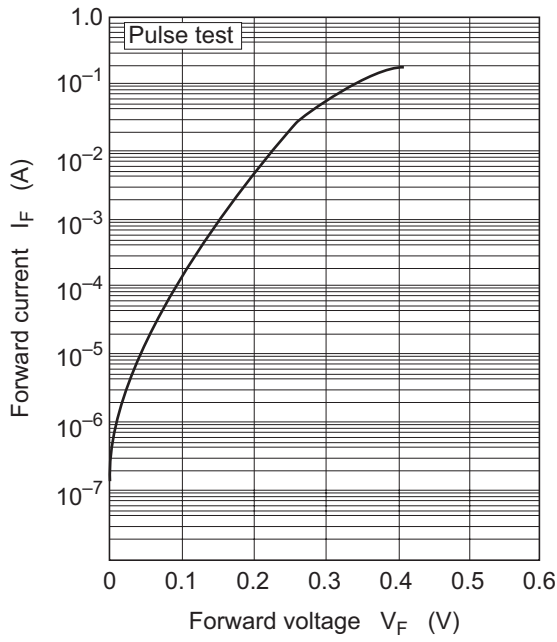


Fig.1 Forward current vs. Forward voltage

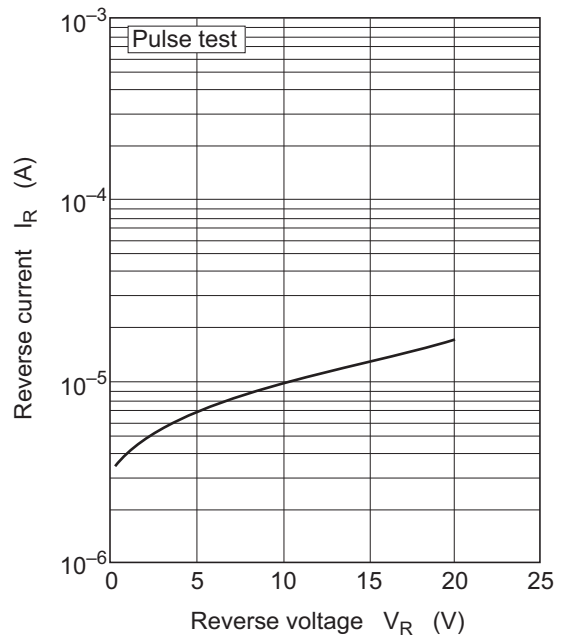


Fig.2 Reverse current vs. Reverse voltage

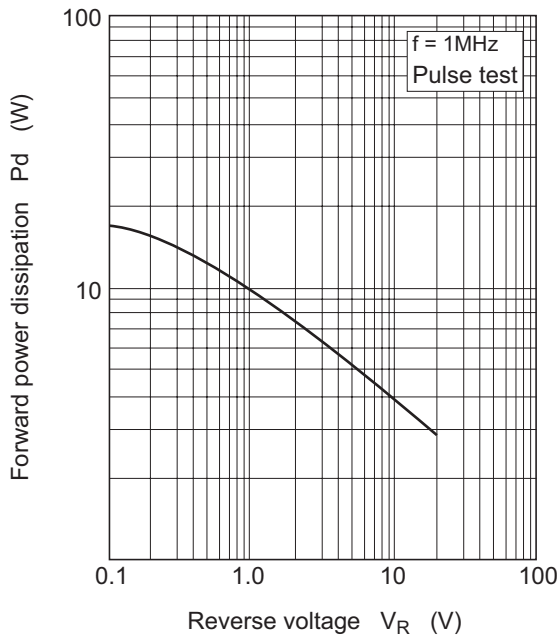


Fig3. Capacitance vs. Reverse oltage

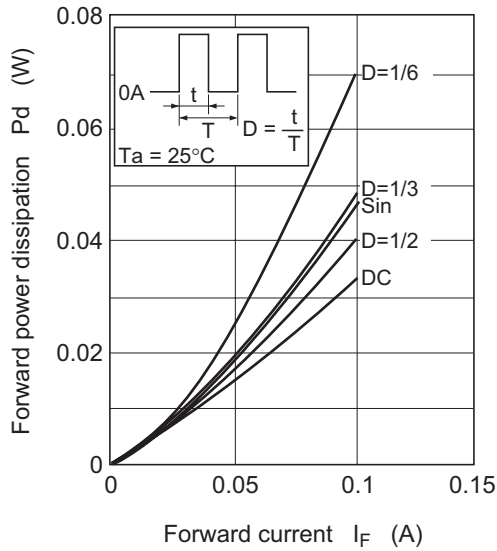


Fig4. Forward power dissipation vs. Forward current

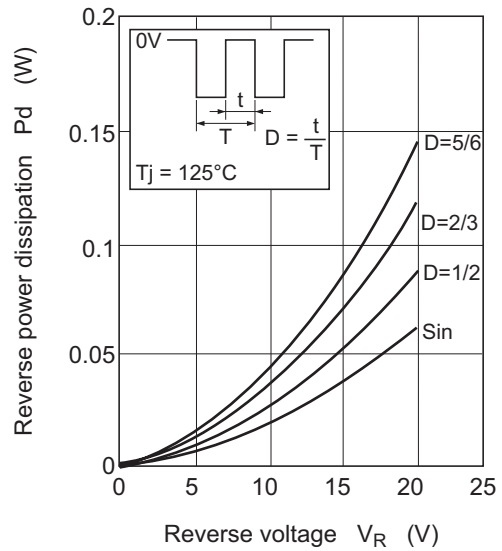


Fig5. Reverse power dissipation vs. Reverse voltage

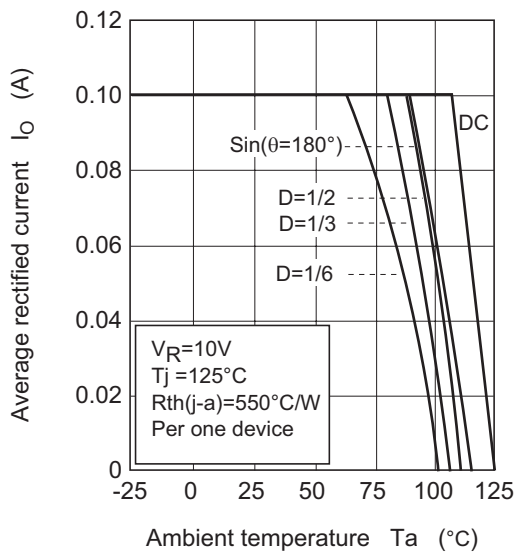
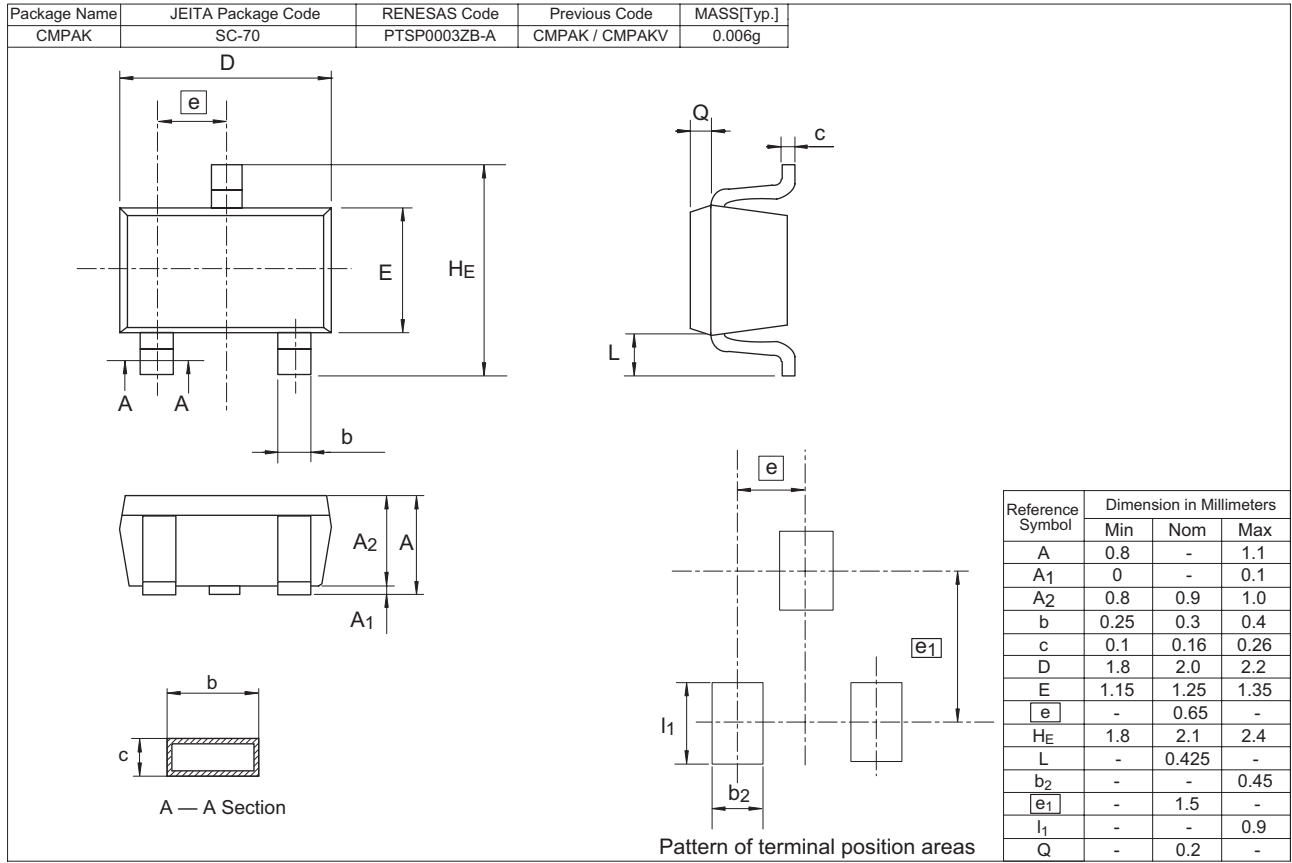


Fig.6 Average rectified current vs. Ambient temperature

Package Dimensions



Notes:

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